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RGS60TS65D

650V 30A Field Stop Trench IGBT

V _{CES}	650V
I _{C(100°C)}	30A
V _{CE(sat) (Typ.)}	1.65V
P_D	223W

Features

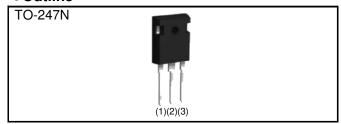
- 1) Low Collector Emitter Saturation Voltage
- 2) Short Circuit Withstand Time 8µs
- 3) Qualified to AEC-Q101
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

Applications

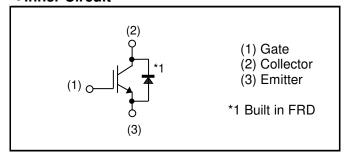
General Inverter

for Automotive and Industrial Use

Outline



●Inner Circuit



Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Tuno	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGS60TS65D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V_{GES}	±30	V
Callactor Current	T _C = 25°C	I _C	56	А
Collector Current	T _C = 100°C	I _C	30	А
Pulsed Collector Current	I _{CP} *1	90	А	
D: 1.5	T _C = 25°C	I _F	56	А
Diode Forward Current	T _C = 100°C	I _F	30	А
Diode Pulsed Forward Current		I _{FP} *1	90	А
B. B. J. J.	T _C = 25°C	P _D	223	W
Power Dissipation	T _C = 100°C	P _D	111	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax.}

●Thermal Resistance

Parameter	Symbol	Values			Unit
Parameter		Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	0.67	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	1.17	°C/W

ullet IGBT Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
i didilielei	Syllibol		Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_C = 10 \mu A, V_{GE} = 0 V$	650	-	-	٧
		$V_{CE} = 650V, V_{GE} = 0V$				
Collector Cut - off Current	I _{CES}	T _j = 25°C	-	-	10	μΑ
		T _j = 175°C			5	mA
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, \ V_{CE} = 0V$	-	-	±200	nA
Gate - Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$V_{CE} = 5V, I_{C} = 1.5mA$	5.0	6.0	7.0	V
		$I_C = 30A, V_{GE} = 15V$				
Collector - Emitter Saturation Voltage	$V_{CE(sat)}$	T _j = 25°C	-	1.65	2.10	V
		T _j = 175°C	-	2.15	-	

ullet IGBT Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Davamatav	Symbol	Conditions -		Unit		
Parameter	Symbol		Min.	Тур.	Max.	Offic
Input Capacitance	C_{ies}	V _{CE} = 30V	-	980	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$	-	80	-	pF
Reverse Transfer Capacitance	C _{res}	f = 1MHz	-	13	-	
Total Gate Charge	Q_g	V _{CE} = 300V	-	36	-	
Gate - Emitter Charge	Q_{ge}	I _C = 30A	-	10	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	15	-	
Turn - on Delay Time	t _{d(on)}	$I_C = 30A, V_{CC} = 400V$	-	28	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	12	-	no
Turn - off Delay Time	$t_{d(off)}$	T _j = 25°C	-	104	-	ns
Fall Time	t _f	Inductive Load	-	101	-	
Turn - on Switching Loss	E _{on}	*E _{on} includes diode	-	0.66	-	m l
Turn - off Switching Loss	E_{off}	reverse recovery	-	0.81	-	mJ
Turn - on Delay Time	t _{d(on)}	$I_C = 30A, V_{CC} = 400V$	-	29	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	17	-	no
Turn - off Delay Time	$t_{d(off)}$	T _j = 175°C	-	131	-	ns
Fall Time	t _f	Inductive Load	-	159	-	
Turn - on Switching Loss	E _{on}	*E _{on} includes diode	-	0.88	-	m l
Turn - off Switching Loss	E _{off}	reverse recovery	-	1.13	-	mJ
		$I_C = 90A, V_{CC} = 520V$				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 650V, V_{GE} = 15V$	FULL SQUARE			-
		$R_G = 50\Omega, T_j = 175^{\circ}C$				
Short Circuit Withstand Time	t _{sc}	$V_{CC} \le 360V$	0			
		$V_{GE} = 15V, T_j = 25^{\circ}C$	8	-	-	μs
Short Circuit Withstand Time	t _{sc} *2	$V_{CC} \le 360V$	6	-	-	μs
	ι _{sc} –	$V_{GE} = 15V, T_j = 150^{\circ}C$	0			

^{*2} Design assurance without measurement

•FRD Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Тур.	Max.	Offic
Diode Forward Voltage	V_{F}	$I_F = 30A$ $T_j = 25$ °C $T_j = 175$ °C	-	1.45 1.55	1.90 -	V
Diode Reverse Recovery Time	t _{rr}		-	103	-	ns
Diode Peak Reverse Recovery Current	I _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	7.1	-	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.4	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	15	-	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 30A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	242	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	9.8	ı	Α
Diode Reverse Recovery Charge	Q_{rr}		-	1.3	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	113	-	μJ

Fig.1 Power Dissipation vs. Case Temperature

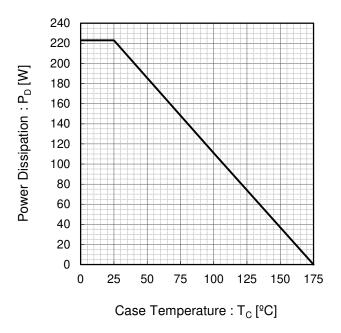


Fig.2 Collector Current vs. Case Temperature

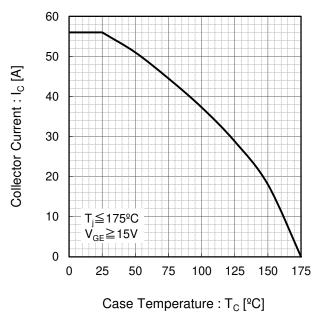


Fig.3 Forward Bias Safe Operating Area

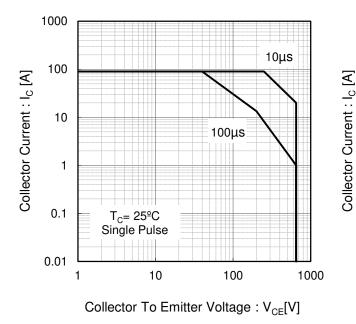


Fig.4 Reverse Bias Safe Operating Area

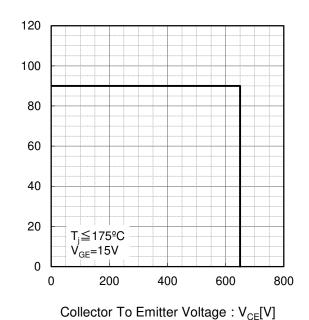


Fig.5 Typical Output Characteristics

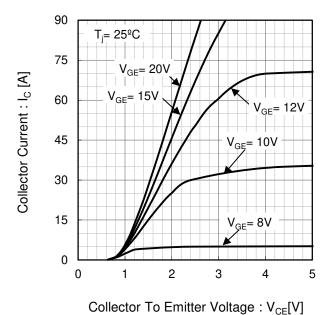
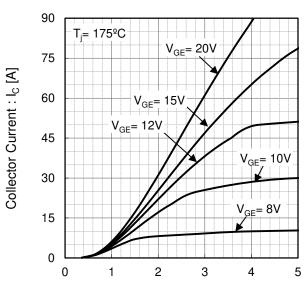


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage: V_{CE}[V]

Fig.7 Typical Transfer Characteristics

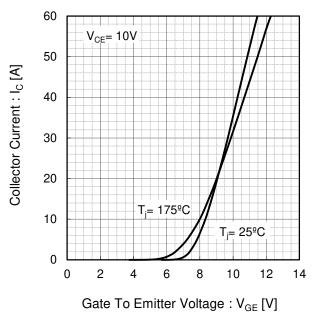


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature

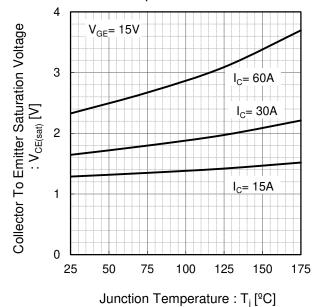
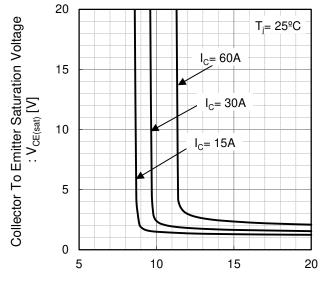
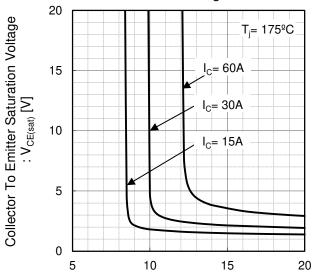


Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V_{GE} [V]

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage: V_{GE} [V]

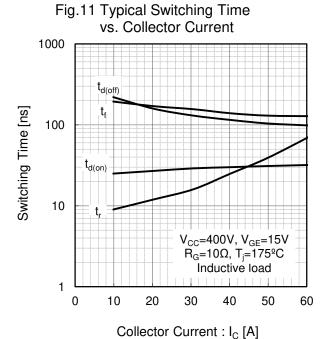


Fig.12 Typical Switching Time vs. Gate Resistance 1000 Switching Time [ns] 100 $t_{d(off)}$ $t_{d(on)}$ 10 V_{CC} =400V, I_{C} =30A V_{GE} =15V, T_{j} =175 $^{\circ}$ C Inductive load 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] $\mathsf{E}_{\mathsf{off}}$ 0.1 V_{CC} =400V, V_{GE} =15V R_{G} =10 Ω , T_{j} =175 $^{\circ}$ C Inductive load 0.01 40 0 10 20 30 50 60 Collector Current : I_C [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] $\mathsf{E}_{\mathsf{off}}$ 1 E_{on} 0.1 V_{CC} =400V, I_{C} =30A V_{GE} =15V, T_{j} =175 $^{\circ}$ C Inductive load 0.01 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] Coes 100 Cres 10 f=1MHz $V_{GE}=0V$ T_i=25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage: V_{CE}[V]

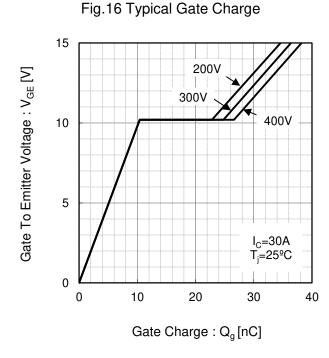


Fig.17 Typical Diode Forward Current vs. Forward Voltage 90 75 Forward Current : I_F [A] 60 45 30 15 T_i= 175ºC T_i= 25ºC 0 0.5 1.5 2 2.5 3 Forward Voltage : V_F[V]

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400 Reverse Recovery Time: trr [ns] 300 T_i= 175ºC 200 100 V_{CC} =400V di_F/dt =200A/ μ s T_i= 25ºC Inductive load 0 40 50 0 20 30 60 10 Forward Current : I_F [A]

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

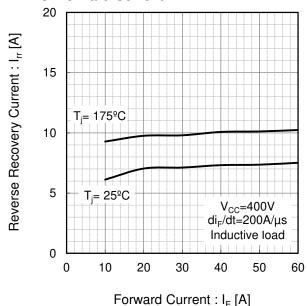
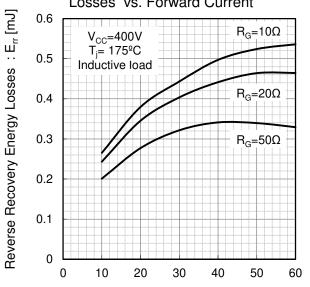
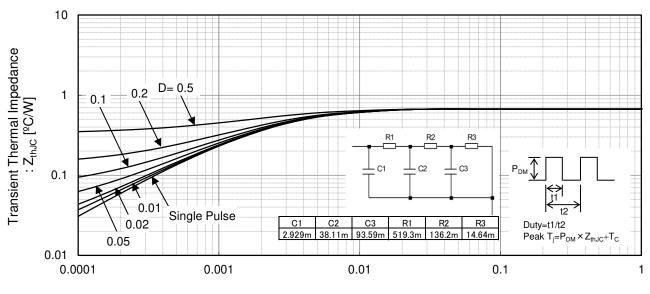


Fig.20 Typical Diode Reverse Recovery Energy Losses vs. Forward Current



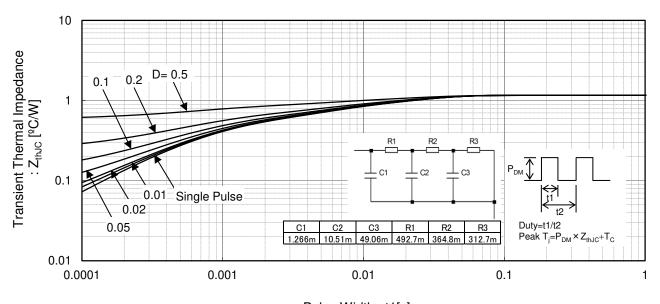
Forward Current : I_F [A]

Fig.21 IGBT Transient Thermal Impedance



Pulse Width: t1[s]

Fig.22 Diode Transient Thermal Impedance



Pulse Width: t1[s]

●Inductive Load Switching Circuit and Waveform

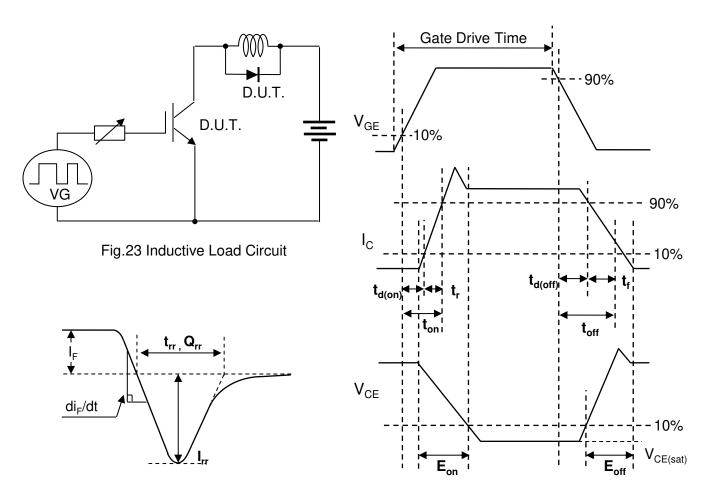


Fig.25 Diode Reverce Recovery Waveform

Fig.24 Inductive Load Waveform

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